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Kind regards,

Team Nexperia

# 74AUP1G80

Low-power D-type flip-flop; positive-edge trigger

Rev. 4 — 28 June 2012

Product data sheet

## 1. General description

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The 74AUP1G80 provides the single positive-edge triggered D-type flip-flop. Information on the data input is transferred to the Q output on the LOW-to-HIGH transition of the clock pulse. The input pin D must be stable one set-up time prior to the LOW-to-HIGH clock transition for predictable operation.

Schmitt trigger action at all inputs makes the circuit tolerant to slower input rise and fall times across the entire  $V_{CC}$  range from 0.8 V to 3.6 V.

This device ensures a very low static and dynamic power consumption across the entire  $V_{CC}$  range from 0.8 V to 3.6 V.

This device is fully specified for partial power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

## 2. Features and benefits

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- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- Complies with JEDEC standards:
  - ◆ JESD8-12 (0.8 V to 1.3 V)
  - ◆ JESD8-11 (0.9 V to 1.65 V)
  - ◆ JESD8-7 (1.2 V to 1.95 V)
  - ◆ JESD8-5 (1.8 V to 2.7 V)
  - ◆ JESD8-B (2.7 V to 3.6 V)
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 5000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
  - ◆ CDM JESD22-C101E exceeds 1000 V
- Low static power consumption;  $I_{CC} = 0.9 \mu\text{A}$  (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10 % of  $V_{CC}$
- $I_{OFF}$  circuitry provides partial power-down mode operation
- Multiple package options
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$



### 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74AUP1G80GW	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74AUP1G80GM	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74AUP1G80GF	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm	SOT891
74AUP1G80GN	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm	SOT1115
74AUP1G80GS	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	SOT1202
74AUP1G80GX	-40 °C to +125 °C	X2SON5	X2SON5: plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 × 0.8 × 0.35 mm	SOT1226

### 4. Marking

Table 2. Marking

Type number	Marking code <sup>[1]</sup>
74AUP1G80GW	pT
74AUP1G80GM	pT
74AUP1G80GF	pT
74AUP1G80GN	pT
74AUP1G80GS	pT
74AUP1G80GX	pT

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

### 5. Functional diagram

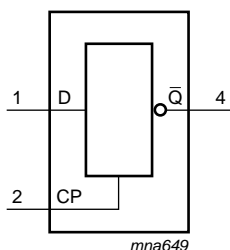


Fig 1. Logic symbol

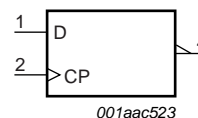
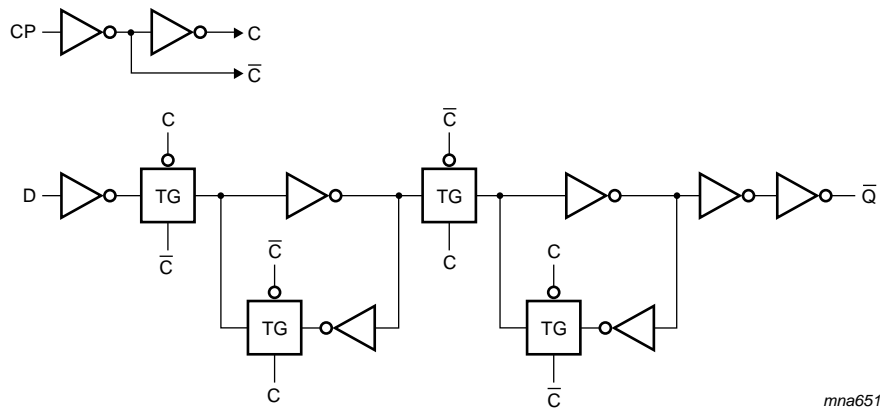


Fig 2. IEC logic symbol



mna651

Fig 3. Logic diagram

## 6. Pinning information

### 6.1 Pinning

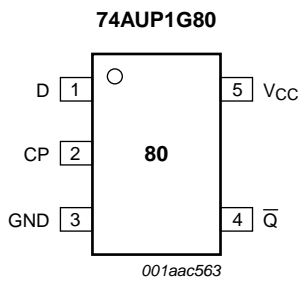


Fig 4. Pin configuration SOT353-1

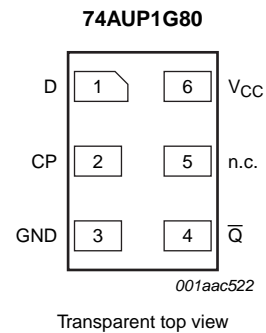


Fig 5. Pin configuration SOT886

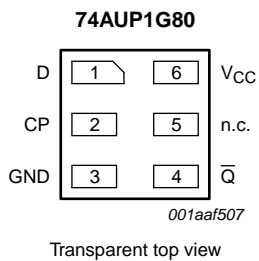


Fig 6. Pin configuration SOT891, SOT1115 and SOT1202

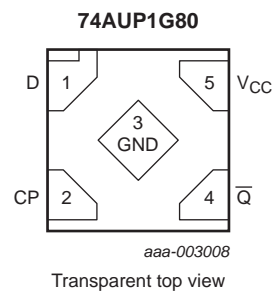


Fig 7. Pin configuration SOT1226 (X2SON5)

## 6.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	TSSOP5 and X2SON5	XSON6	
D	1	1	data input
CP	2	2	clock pulse input
GND	3	3	ground (0 V)
$\overline{Q}$	4	4	data output
n.c.	-	5	not connected
V <sub>CC</sub>	5	6	supply voltage

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

Input		Output
CP	D	$\overline{Q}$
↑	L	H
↑	H	L
L	X	$\overline{q}$

- [1] H = HIGH voltage level;  
 L = LOW voltage level;  
 ↑ = LOW-to-HIGH CP transition;  
 X = don't care;  
 $\overline{q}$  = lower case letter indicates the state of referenced input, one set-up time prior to the LOW-to-HIGH CP transition.

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+4.6	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < 0 V	-50	-	mA
V <sub>I</sub>	input voltage		[1] -0.5	+4.6	V
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < 0 V	-50	-	mA
V <sub>O</sub>	output voltage	Active mode and Power-down mode	[1] -0.5	+4.6	V
I <sub>O</sub>	output current	V <sub>O</sub> = 0 V to V <sub>CC</sub>	-	+20	mA
I <sub>CC</sub>	supply current		-	50	mA
I <sub>GND</sub>	ground current		-50	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C	[2] -	250	mW

- [1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

- [2] For TSSOP5 packages: above 87.5 °C the value of P<sub>tot</sub> derates linearly with 4.0 mW/K.  
 For XSON6 and X2SON5 packages: above 118 °C the value of P<sub>tot</sub> derates linearly with 7.8 mW/K.

## 9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		0.8	3.6	V
$V_I$	input voltage		0	3.6	V
$V_O$	output voltage	Active mode and Power-down mode	0	3.6	V
$T_{amb}$	ambient temperature		-40	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 0.8\text{ V to }3.6\text{ V}$	0	200	ns/V

## 10. Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{amb} = 25\text{ °C}$						
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 0.8\text{ V}$	$0.70 \times V_{CC}$	-	-	V
		$V_{CC} = 0.9\text{ V to }1.95\text{ V}$	$0.65 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.6	-	-	V
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	2.0	-	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 0.8\text{ V}$	-	-	$0.30 \times V_{CC}$	V
		$V_{CC} = 0.9\text{ V to }1.95\text{ V}$	-	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	-	-	0.7	V
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	-	-	0.9	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$I_O = -20\text{ }\mu\text{A}; V_{CC} = 0.8\text{ V to }3.6\text{ V}$	$V_{CC} - 0.1$	-	-	V
		$I_O = -1.1\text{ mA}; V_{CC} = 1.1\text{ V}$	$0.75 \times V_{CC}$	-	-	V
		$I_O = -1.7\text{ mA}; V_{CC} = 1.4\text{ V}$	1.11	-	-	V
		$I_O = -1.9\text{ mA}; V_{CC} = 1.65\text{ V}$	1.32	-	-	V
		$I_O = -2.3\text{ mA}; V_{CC} = 2.3\text{ V}$	2.05	-	-	V
		$I_O = -3.1\text{ mA}; V_{CC} = 2.3\text{ V}$	1.9	-	-	V
		$I_O = -2.7\text{ mA}; V_{CC} = 3.0\text{ V}$	2.72	-	-	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$I_O = 20\text{ }\mu\text{A}; V_{CC} = 0.8\text{ V to }3.6\text{ V}$	-	-	0.1	V
		$I_O = 1.1\text{ mA}; V_{CC} = 1.1\text{ V}$	-	-	$0.3 \times V_{CC}$	V
		$I_O = 1.7\text{ mA}; V_{CC} = 1.4\text{ V}$	-	-	0.31	V
		$I_O = 1.9\text{ mA}; V_{CC} = 1.65\text{ V}$	-	-	0.31	V
		$I_O = 2.3\text{ mA}; V_{CC} = 2.3\text{ V}$	-	-	0.31	V
		$I_O = 3.1\text{ mA}; V_{CC} = 2.3\text{ V}$	-	-	0.44	V
		$I_O = 2.7\text{ mA}; V_{CC} = 3.0\text{ V}$	-	-	0.31	V
$I_I$	input leakage current	$V_I = \text{GND to }3.6\text{ V}; V_{CC} = 0\text{ V to }3.6\text{ V}$	-	-	$\pm 0.1$	$\mu\text{A}$

**Table 7. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{OFF}$	power-off leakage current	$V_I$ or $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V	-	-	$\pm 0.2$	$\mu$ A
$\Delta I_{OFF}$	additional power-off leakage current	$V_I$ or $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V to 0.2 V	-	-	$\pm 0.2$	$\mu$ A
$I_{CC}$	supply current	$V_I = GND$ or $V_{CC}$ ; $I_O = 0$ A; $V_{CC} = 0.8$ V to 3.6 V	-	-	0.5	$\mu$ A
$\Delta I_{CC}$	additional supply current	$V_I = V_{CC} - 0.6$ V; $I_O = 0$ A; $V_{CC} = 3.3$ V	<a href="#">[1]</a> -	-	40	$\mu$ A
$C_I$	input capacitance	$V_{CC} = 0$ V to 3.6 V; $V_I = GND$ or $V_{CC}$	-	1.5	-	pF
$C_O$	output capacitance	$V_O = GND$ ; $V_{CC} = 0$ V	-	3.0	-	pF
<b><math>T_{amb} = -40</math> °C to <math>+85</math> °C</b>						
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 0.8$ V	$0.70 \times V_{CC}$	-	-	V
		$V_{CC} = 0.9$ V to 1.95 V	$0.65 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3$ V to 2.7 V	1.6	-	-	V
		$V_{CC} = 3.0$ V to 3.6 V	2.0	-	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 0.8$ V	-	-	$0.30 \times V_{CC}$	V
		$V_{CC} = 0.9$ V to 1.95 V	-	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3$ V to 2.7 V	-	-	0.7	V
		$V_{CC} = 3.0$ V to 3.6 V	-	-	0.9	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$I_O = -20$ $\mu$ A; $V_{CC} = 0.8$ V to 3.6 V	$V_{CC} - 0.1$	-	-	V
		$I_O = -1.1$ mA; $V_{CC} = 1.1$ V	$0.7 \times V_{CC}$	-	-	V
		$I_O = -1.7$ mA; $V_{CC} = 1.4$ V	1.03	-	-	V
		$I_O = -1.9$ mA; $V_{CC} = 1.65$ V	1.30	-	-	V
		$I_O = -2.3$ mA; $V_{CC} = 2.3$ V	1.97	-	-	V
		$I_O = -3.1$ mA; $V_{CC} = 2.3$ V	1.85	-	-	V
		$I_O = -2.7$ mA; $V_{CC} = 3.0$ V	2.67	-	-	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$I_O = 20$ $\mu$ A; $V_{CC} = 0.8$ V to 3.6 V	-	-	0.1	V
		$I_O = 1.1$ mA; $V_{CC} = 1.1$ V	-	-	$0.3 \times V_{CC}$	V
		$I_O = 1.7$ mA; $V_{CC} = 1.4$ V	-	-	0.37	V
		$I_O = 1.9$ mA; $V_{CC} = 1.65$ V	-	-	0.35	V
		$I_O = 2.3$ mA; $V_{CC} = 2.3$ V	-	-	0.33	V
		$I_O = 3.1$ mA; $V_{CC} = 2.3$ V	-	-	0.45	V
		$I_O = 2.7$ mA; $V_{CC} = 3.0$ V	-	-	0.33	V
$I_I$	input leakage current	$V_I = GND$ to 3.6 V; $V_{CC} = 0$ V to 3.6 V	-	-	$\pm 0.5$	$\mu$ A
		$V_I$ or $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V	-	-	$\pm 0.5$	$\mu$ A
$\Delta I_{OFF}$	additional power-off leakage current	$V_I$ or $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V to 0.2 V	-	-	$\pm 0.6$	$\mu$ A

**Table 7. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{CC}$	supply current	$V_I = \text{GND or } V_{CC}; I_O = 0 \text{ A};$ $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	0.9	$\mu\text{A}$
$\Delta I_{CC}$	additional supply current	$V_I = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A};$ $V_{CC} = 3.3 \text{ V}$	[1]	-	50	$\mu\text{A}$
<b><math>T_{\text{amb}} = -40 \text{ }^\circ\text{C to } +125 \text{ }^\circ\text{C}</math></b>						
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 0.8 \text{ V}$	$0.75 \times V_{CC}$	-	-	V
		$V_{CC} = 0.9 \text{ V to } 1.95 \text{ V}$	$0.70 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.6	-	-	V
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	2.0	-	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 0.8 \text{ V}$	-	-	$0.25 \times V_{CC}$	V
		$V_{CC} = 0.9 \text{ V to } 1.95 \text{ V}$	-	-	$0.30 \times V_{CC}$	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	-	-	0.7	V
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	-	-	0.9	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$				
		$I_O = -20 \mu\text{A}; V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	$V_{CC} - 0.11$	-	-	V
		$I_O = -1.1 \text{ mA}; V_{CC} = 1.1 \text{ V}$	$0.6 \times V_{CC}$	-	-	V
		$I_O = -1.7 \text{ mA}; V_{CC} = 1.4 \text{ V}$	0.93	-	-	V
		$I_O = -1.9 \text{ mA}; V_{CC} = 1.65 \text{ V}$	1.17	-	-	V
		$I_O = -2.3 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.77	-	-	V
		$I_O = -3.1 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.67	-	-	V
		$I_O = -2.7 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.40	-	-	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$				
		$I_O = 20 \mu\text{A}; V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	0.11	V
		$I_O = 1.1 \text{ mA}; V_{CC} = 1.1 \text{ V}$	-	-	$0.33 \times V_{CC}$	V
		$I_O = 1.7 \text{ mA}; V_{CC} = 1.4 \text{ V}$	-	-	0.41	V
		$I_O = 1.9 \text{ mA}; V_{CC} = 1.65 \text{ V}$	-	-	0.39	V
		$I_O = 2.3 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	-	0.36	V
		$I_O = 3.1 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	-	0.50	V
		$I_O = 2.7 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.36	V
$I_I$	input leakage current	$V_I = \text{GND to } 3.6 \text{ V}; V_{CC} = 0 \text{ V to } 3.6 \text{ V}$	-	-	$\pm 0.75$	$\mu\text{A}$
		$V_I \text{ or } V_O = 0 \text{ V to } 3.6 \text{ V}; V_{CC} = 0 \text{ V}$	-	-	$\pm 0.75$	$\mu\text{A}$
$I_{OFF}$	power-off leakage current	$V_I \text{ or } V_O = 0 \text{ V to } 3.6 \text{ V};$ $V_{CC} = 0 \text{ V to } 0.2 \text{ V}$	-	-	$\pm 0.75$	$\mu\text{A}$
$\Delta I_{OFF}$	additional power-off leakage current	$V_I \text{ or } V_O = 0 \text{ V to } 3.6 \text{ V};$ $V_{CC} = 0 \text{ V to } 0.2 \text{ V}$	-	-	$\pm 0.75$	$\mu\text{A}$
$I_{CC}$	supply current	$V_I = \text{GND or } V_{CC}; I_O = 0 \text{ A};$ $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	1.4	$\mu\text{A}$
$\Delta I_{CC}$	additional supply current	$V_I = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A};$ $V_{CC} = 3.3 \text{ V}$	[1]	-	75	$\mu\text{A}$

[1] One input at  $V_{CC} - 0.6 \text{ V}$ , other input at  $V_{CC}$  or GND.



## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**

 Voltages are referenced to GND (ground = 0 V; for test circuit see [Figure 10](#))

Symbol	Parameter	Conditions	25 °C			–40 °C to +125 °C				Unit
			Min	Typ <sup>[1]</sup>	Max	Min (85 °C)	Max (85 °C)	Min (125 °C)	Max (125 °C)	
<b>C<sub>L</sub> = 5 pF</b>										
t <sub>pd</sub>	propagation delay	CP to $\bar{Q}$ ; see <a href="#">Figure 8</a> <sup>[2]</sup>	-	20.9	-	-	-	-	-	ns
		V <sub>CC</sub> = 0.8 V	-	20.9	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	2.9	6.0	12.9	2.6	14.3	2.6	15.7	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	1.9	4.2	7.6	2.0	8.9	2.0	9.8	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.7	3.4	5.9	1.6	7.0	1.6	7.7	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.4	2.6	4.3	1.2	5.6	1.2	6.2	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.2	2.2	3.6	1.0	4.4	1.0	4.8	ns
f <sub>max</sub>	maximum frequency	CP; see <a href="#">Figure 9</a>	-	53	-	-	-	-	-	MHz
		V <sub>CC</sub> = 0.8 V	-	53	-	-	-	-	-	MHz
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	203	-	170	-	170	-	MHz
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	347	-	310	-	300	-	MHz
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	435	-	400	-	390	-	MHz
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	550	-	490	-	480	-	MHz
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	619	-	550	-	510	-	MHz
<b>C<sub>L</sub> = 10 pF</b>										
t <sub>pd</sub>	propagation delay	CP to $\bar{Q}$ ; see <a href="#">Figure 8</a> <sup>[2]</sup>	-	24.6	-	-	-	-	-	ns
		V <sub>CC</sub> = 0.8 V	-	24.6	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	3.3	6.9	14.9	3.0	16.5	3.0	18.1	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	2.6	4.8	8.8	2.3	10.3	2.3	11.3	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	2.3	3.9	6.8	2.0	8.1	2.0	8.9	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.9	3.1	5.1	1.7	6.3	1.7	6.9	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.8	2.7	4.4	1.4	4.9	1.4	5.4	ns
f <sub>max</sub>	maximum frequency	CP; see <a href="#">Figure 9</a>	-	52	-	-	-	-	-	MHz
		V <sub>CC</sub> = 0.8 V	-	52	-	-	-	-	-	MHz
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	192	-	150	-	150	-	MHz
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	324	-	280	-	230	-	MHz
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	421	-	310	-	250	-	MHz
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	486	-	370	-	360	-	MHz
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	550	-	410	-	360	-	MHz

**Table 8. Dynamic characteristics ...continued**  
 Voltages are referenced to GND (ground = 0 V; for test circuit see [Figure 10](#))

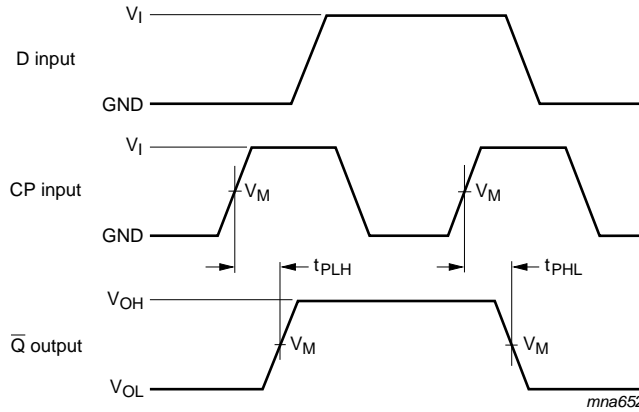
Symbol	Parameter	Conditions	25 °C			–40 °C to +125 °C				Unit
			Min	Typ <sup>[1]</sup>	Max	Min (85 °C)	Max (85 °C)	Min (125 °C)	Max (125 °C)	
<b>C<sub>L</sub> = 15 pF</b>										
t <sub>pd</sub>	propagation delay	CP to $\overline{Q}$ ; see <a href="#">Figure 8</a> <sup>[2]</sup>								
		V <sub>CC</sub> = 0.8 V	-	28.2	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	3.0	7.6	16.7	3.4	18.6	3.4	20.5	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	3.0	5.3	9.8	2.6	11.5	2.6	12.7	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	2.6	4.4	7.6	2.3	9.1	2.3	10.0	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	2.2	3.5	5.7	2.0	6.9	2.0	7.6	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.9	3.1	5.0	1.8	5.5	1.8	6.1	ns
f <sub>max</sub>	maximum frequency	CP; see <a href="#">Figure 9</a>								
		V <sub>CC</sub> = 0.8 V	-	50	-	-	-	-	-	MHz
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	181	-	120	-	120	-	MHz
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	301	-	190	-	160	-	MHz
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	407	-	240	-	190	-	MHz
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	422	-	300	-	270	-	MHz
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	481	-	320	-	300	-	MHz
<b>C<sub>L</sub> = 30 pF</b>										
t <sub>pd</sub>	propagation delay	CP to $\overline{Q}$ ; see <a href="#">Figure 8</a> <sup>[2]</sup>								
		V <sub>CC</sub> = 0.8 V	-	38.8	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	4.9	9.8	20.7	4.4	24.7	4.4	27.2	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	4.0	6.8	12.7	3.5	15.0	3.5	16.5	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	3.5	5.6	9.9	2.2	11.9	2.2	13.0	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	3.1	4.5	7.5	2.8	9.3	2.8	10.2	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.9	4.1	6.4	2.7	7.5	2.7	8.3	ns
f <sub>max</sub>	maximum frequency	CP; see <a href="#">Figure 9</a>								
		V <sub>CC</sub> = 0.8 V	-	28	-	-	-	-	-	MHz
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	128	-	70	-	70	-	MHz
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	206	-	120	-	110	-	MHz
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	262	-	150	-	120	-	MHz
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	269	-	190	-	170	-	MHz
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	309	-	200	-	190	-	MHz
<b>C<sub>L</sub> = 5 pF, 10 pF, 15 pF and 30 pF</b>										
t <sub>su(H)</sub>	set-up time HIGH	D to CP; see <a href="#">Figure 9</a>								
		V <sub>CC</sub> = 0.8 V	-	2.5	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	0.5	-	2.2	-	2.2	-	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	0.3	-	1.1	-	1.1	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	0.3	-	0.8	-	0.8	-	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	0.2	-	0.6	-	0.6	-	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	0.2	-	0.4	-	0.4	-	ns

**Table 8. Dynamic characteristics ...continued**  
 Voltages are referenced to GND (ground = 0 V; for test circuit see [Figure 10](#))

Symbol	Parameter	Conditions	25 °C			-40 °C to +125 °C				Unit
			Min	Typ <sup>[1]</sup>	Max	Min (85 °C)	Max (85 °C)	Min (125 °C)	Max (125 °C)	
t <sub>su(L)</sub>	set-up time LOW	D to CP; see <a href="#">Figure 9</a>								
		V <sub>CC</sub> = 0.8 V	-	1.7	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	0.3	-	2.0	-	2.0	-	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	0.2	-	1.3	-	1.3	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	0.2	-	1.1	-	1.1	-	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	0.3	-	0.8	-	0.8	-	ns
t <sub>h</sub>	hold time	D to CP; see <a href="#">Figure 9</a>								
		V <sub>CC</sub> = 0.8 V	-	-2.1	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	-0.4	-	0.2	-	0.2	-	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	-0.3	-	0.1	-	0.1	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	-0.2	-	0	-	0	-	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-0.2	-	0	-	0	-	ns
t <sub>w</sub>	pulse width	CP HIGH or LOW; see <a href="#">Figure 9</a>								
		V <sub>CC</sub> = 0.8 V	-	5.2	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	1.0	-	3.0	-	3.0	-	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	0.8	-	2.0	-	2.0	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	0.6	-	2.0	-	2.0	-	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	0.5	-	2.0	-	2.0	-	ns
C <sub>PD</sub>	power dissipation capacitance	f <sub>i</sub> = 1 MHz; V <sub>I</sub> = GND to V <sub>CC</sub> <sup>[3]</sup>								
		V <sub>CC</sub> = 0.8 V	-	1.8	-	-	-	-	-	pF
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	1.8	-	-	-	-	-	pF
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	1.9	-	-	-	-	-	pF
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	2.0	-	-	-	-	-	pF
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	2.4	-	-	-	-	-	pF
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	2.9	-	-	-	-	pF	

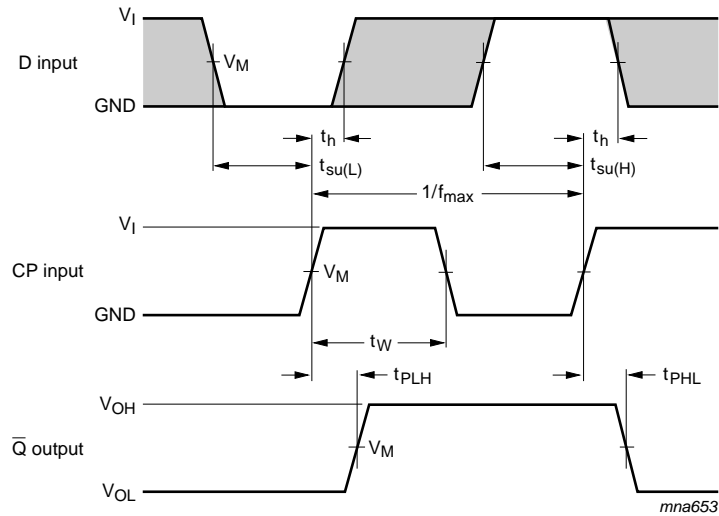
[1] All typical values are measured at nominal V<sub>CC</sub>.  
 [2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.  
 [3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where:  
 f<sub>i</sub> = input frequency in MHz;  
 f<sub>o</sub> = output frequency in MHz;  
 C<sub>L</sub> = output load capacitance in pF;  
 V<sub>CC</sub> = supply voltage in V;  
 N = number of inputs switching;  
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.

12. Waveforms



Measurement points are given in [Table 9](#).  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage drop that occur with the output load.

**Fig 8. The clock input (CP) to output ( $\bar{Q}$ ) propagation delays**

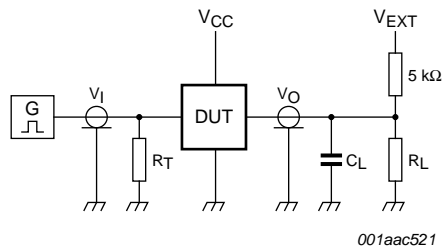


Measurement points are given in [Table 9](#).  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage drop that occur with the output load.

**Fig 9. The clock input (CP) to output ( $\bar{Q}$ ) propagation delays, clock pulse width, D to CP set-up and hold times and the maximum input clock frequency**

**Table 9. Measurement points**

Supply voltage	Output	Input		
$V_{CC}$	$V_M$	$V_M$	$V_I$	$t_r = t_f$
0.8 V to 3.6 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{CC}$	$\leq 3.0$ ns



Test data is given in [Table 10](#).

Definitions for test circuit:

$R_L$  = Load resistance.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

$V_{EXT}$  = External voltage for measuring switching times.

**Fig 10. Test circuit for measuring switching times**

**Table 10. Test data**

Supply voltage	Load		$V_{EXT}$		
$V_{CC}$	$C_L$	$R_L$ [1]	$t_{PLH}$ , $t_{PHL}$	$t_{PZH}$ , $t_{PHZ}$	$t_{PZL}$ , $t_{PLZ}$
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 kΩ or 1 MΩ	open	GND	$2 \times V_{CC}$

[1] For measuring enable and disable times  $R_L = 5 \text{ k}\Omega$ , for measuring propagation delays, setup and hold times and pulse width  $R_L = 1 \text{ M}\Omega$ .

13. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1

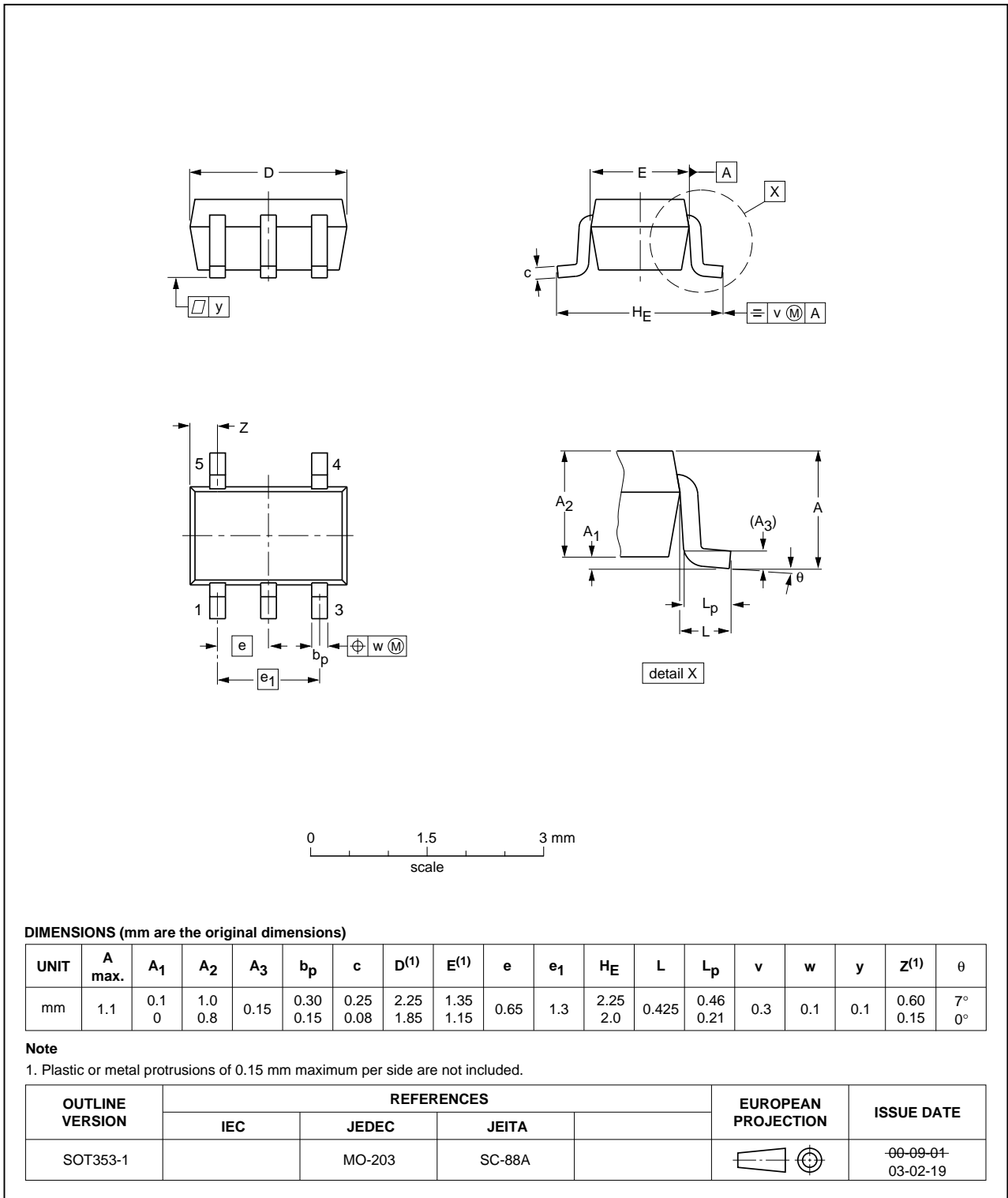


Fig 11. Package outline SOT353-1 (TSSOP5)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

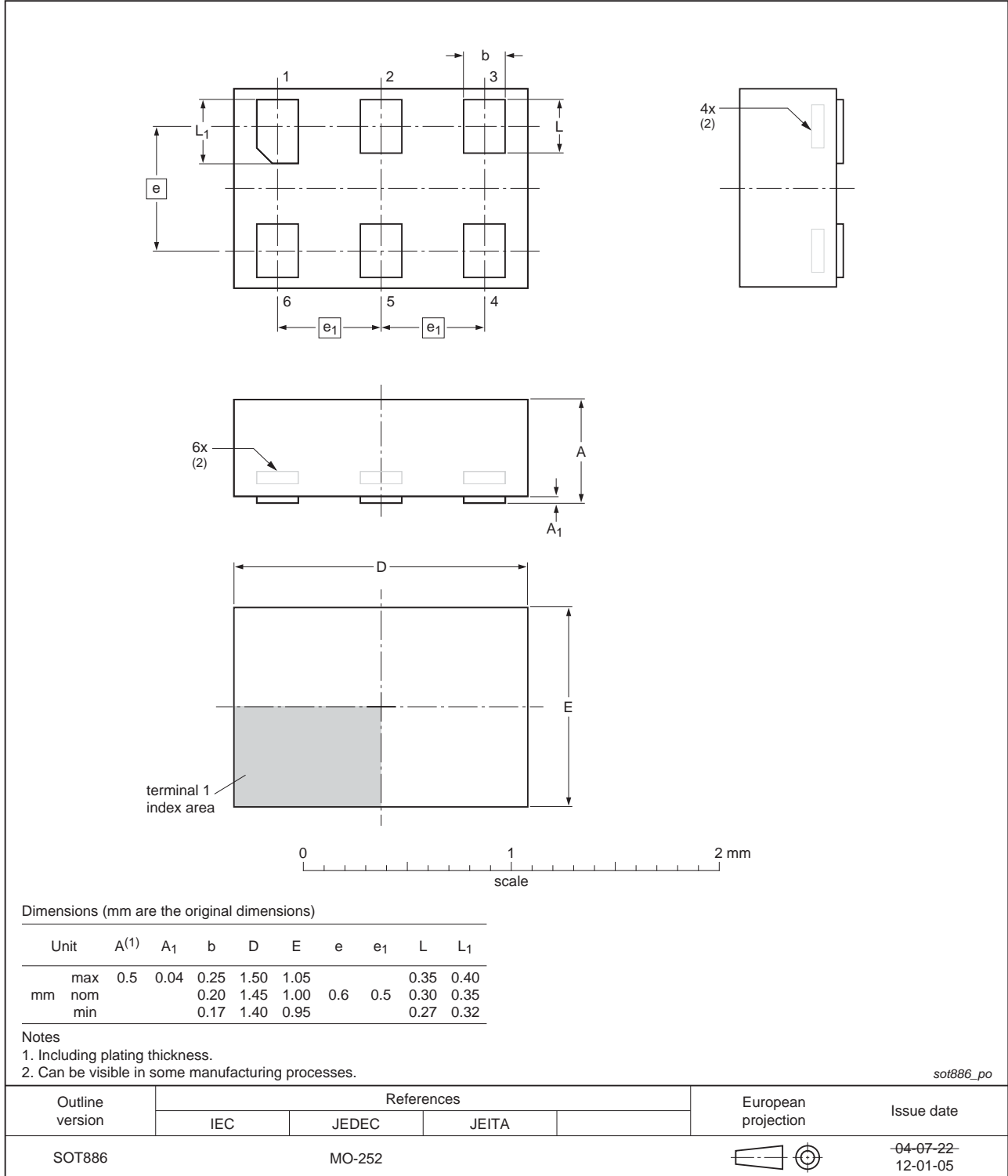


Fig 12. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm

SOT891

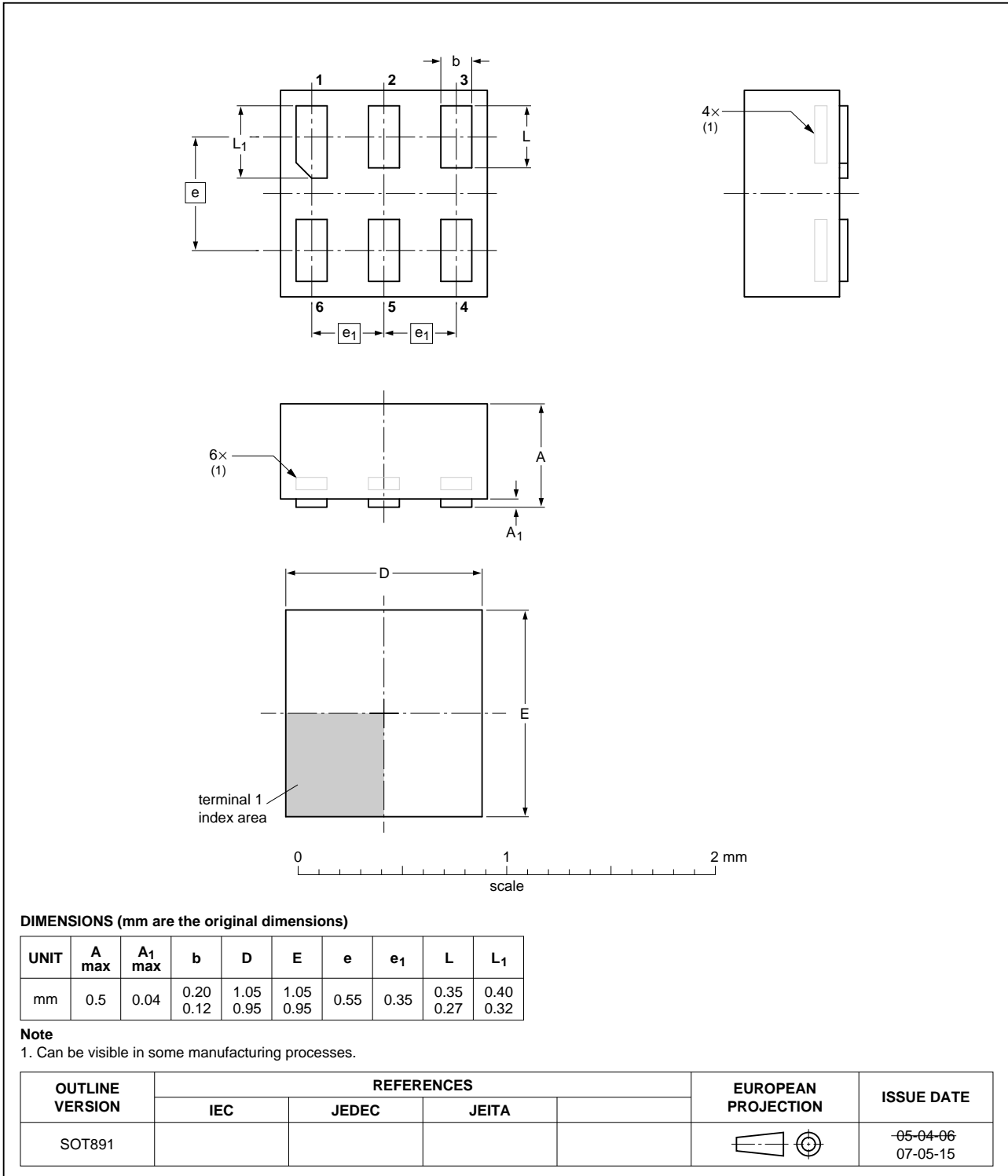


Fig 13. Package outline SOT891 (XSON6)



**XSON6: extremely thin small outline package; no leads;  
6 terminals; body 0.9 x 1.0 x 0.35 mm**

SOT1115

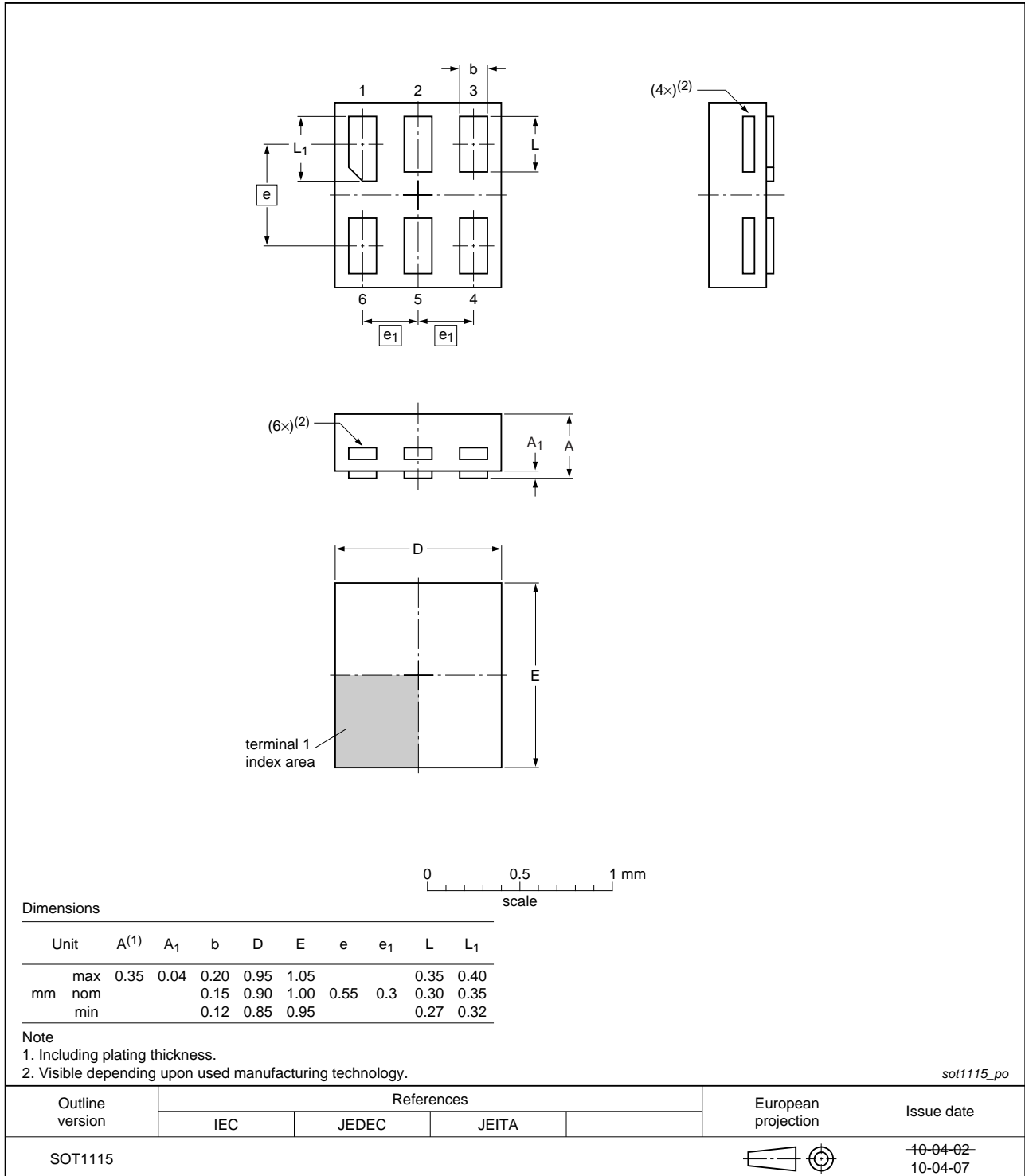


Fig 14. Package outline SOT1115 (XSON6)

**XSON6: extremely thin small outline package; no leads;**  
**6 terminals; body 1.0 x 1.0 x 0.35 mm**

SOT1202

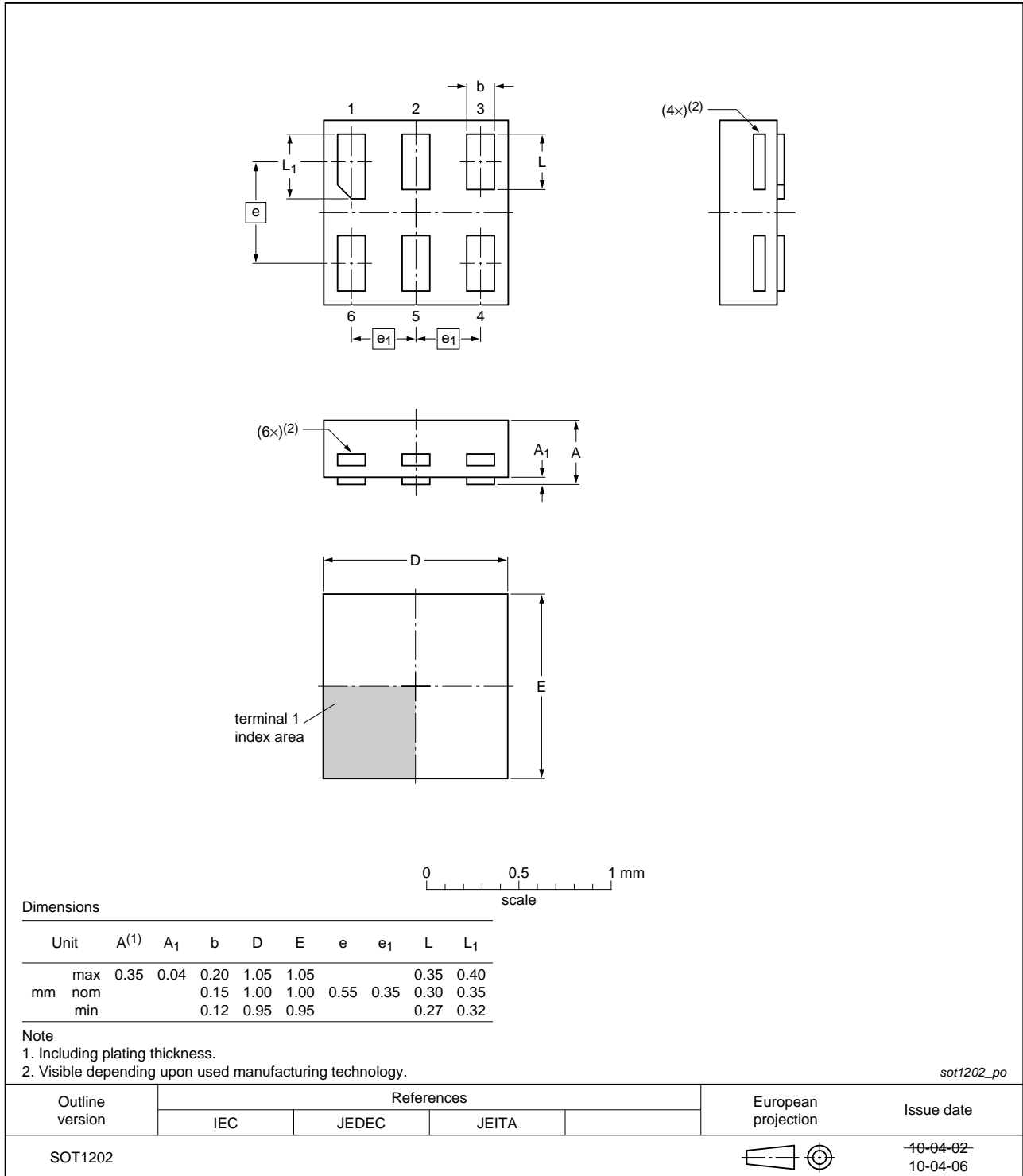


Fig 15. Package outline SOT1202 (XSON6)

X2SON5: plastic thermal enhanced extremely thin small outline package; no leads;  
5 terminals; body 0.8 x 0.8 x 0.35 mm

SOT1226

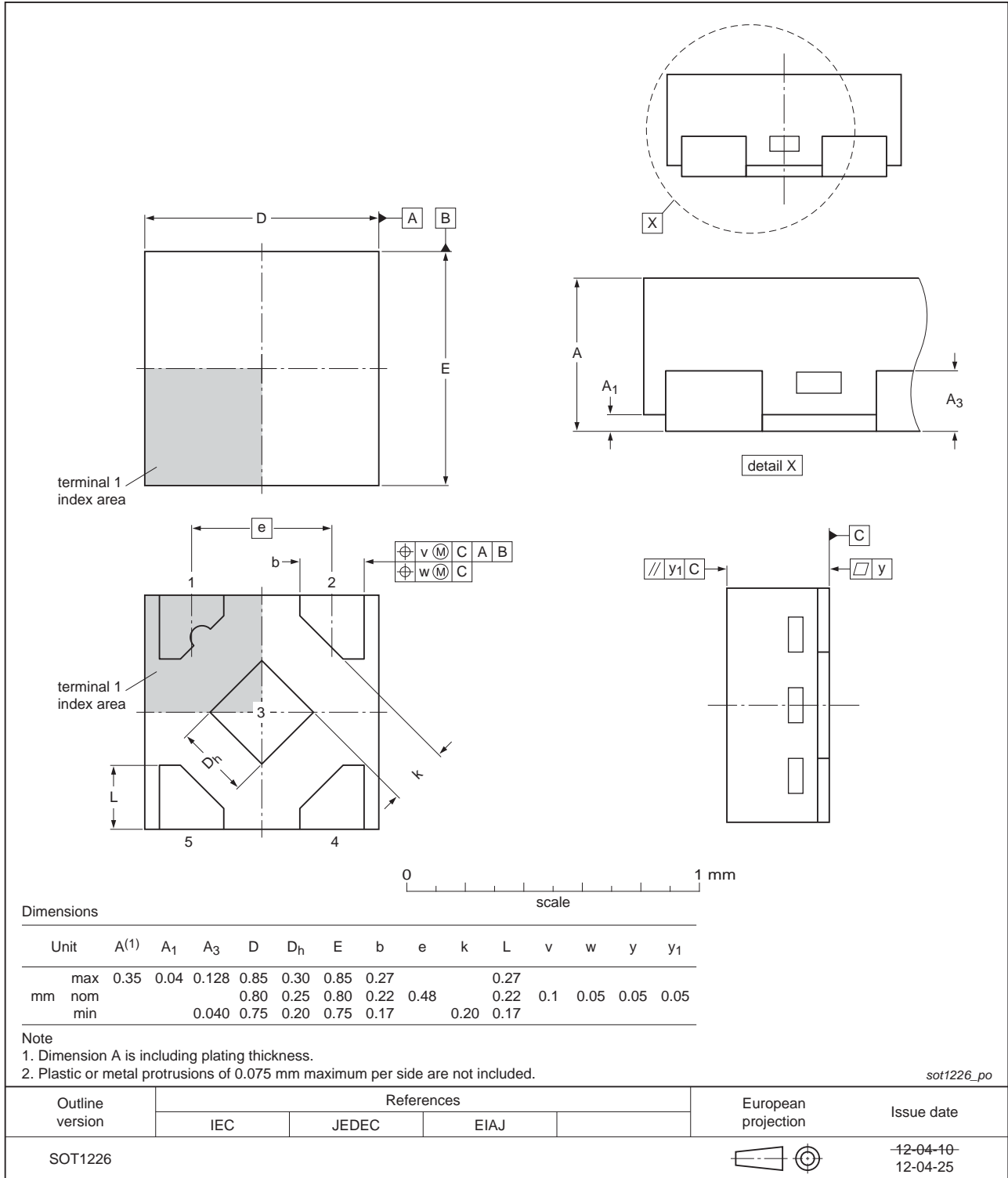


Fig 16. Package outline SOT1226 (X2SON5)

## 14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

## 15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP1G80 v.4	20120628	Product data sheet	-	74AUP1G80 v.3
Modifications:	<ul style="list-style-type: none"> <li>Added type number 74AUP1G80GX (SOT1226)</li> <li>Package outline drawing of SOT886 (<a href="#">Figure 11</a>) modified.</li> </ul>			
74AUP1G80 v.3	20111129	Product data sheet	-	74AUP1G80 v.2
Modifications:	<ul style="list-style-type: none"> <li>Legal pages updated.</li> </ul>			
74AUP1G80 v.2	20100915	Product data sheet	-	74AUP1G80 v.1
74AUP1G80 v.1	20061020	Product data sheet	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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